



FORM PTO-1449
LIST OF PATENTS AND
APPLICANT'S INFORMATION DISCLOSURE STATEMENT

ATTORNEY DOCKET NO.: 29906

SERIAL NO.: 10/091,382

FILING DATE: March 5, 2002

APPLICANT: AMMAR ET AL.

GROUP:

REFERENCE DESIGNATION		U.S. PATENT DOCUMENTS					
EXAMINER INITIALS		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING IF APPROPRIATE
PN	AA	5,423,080	06/06/95	Perret et al.	455	90	
PN	AB	6,040,739	03/21/00	Wedeen et al.	330	66	
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						

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FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION Yes -- No
PN	AK	0 901 181 A2	10.03.1999	EP	H01P5	08	
PN	AL	WO 02/23674 A2	21.03.2002	PCT	H01Q21	00	
	AM						

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)							
PN	AN		Prabhu, et al., "Co-Fired Ceramic on Metal Multichip Modules for Advanced Military Packaging," Aerospace and Electronics Conference, Proceedings of the IEEE, May 24, 1993, pp. 217-222.				
PN	AO		Jayaraj, et al., "RF Characterization of a Low Cost Multichip Packaging Technology For Monolithic Microwave and Millimeter Wave Integrated Circuits," Signals, Systems and Electronics, International Symposium on San Francisco, October 25, 1995, pp. 443-446.				
PN	AP		Gutierrez, et al., "A Thick Film Package for Microwave ICs," Proceedings of the Electronic Component and Technology Conference, May 18, 1992, pp. 151-156.				
	AQ						

EXAMINER:	<i>Patricia Nguyen</i>	DATE CONSIDERED:
		<i>7/10/2003</i>

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; * Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.